

Application No. 10/786,578
Amendment dated October 17, 2005
Reply to Office Action of July 8, 2005

Docket No. CM08657LL

Amendment to the Abstract of the Disclosure:

Please amend the Abstract of the Disclosure as follows:

A solid solder element (106), such as a solder ~~perform~~ preform, is attached onto a contact surface of interest (102), such as a heat sink using an adhesive material (104). Placement of the adhesive material overcomes alignment and registration issues that may interfere with good contact to components (108), such as transistors, during the manufacturing/assembly process, such as a reflow process.